

Electronic Patent Application Fee Transmittal

Application Number:	10755042			
Filing Date:	09-Jan-2004			
Title of Invention:	Integrated chip package structure using silicon substrate and method of manufacturing the same			
First Named Inventor/Applicant Name:	Mou-Shiung Lin			
Filer:	Winston Hsu			
Attorney Docket Number:	MEGP0004USA1			

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Extension - 1 month with \$0 paid	1251	1	120	120
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				120